



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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## Magnetics modules for LAN applications

1000 Base-T magnetics module

**Series/Type:** B78476A8066A003

**Date:** March 2015

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### SMD

#### Features

- Ferrite toroid, case and potting (UL 94 V-0)
- Compliant with IPC/JEDEC J-STD-020D
- Compliant with IEEE 802.3af
- Optimized for full duplex applications
- RoHS-compatible

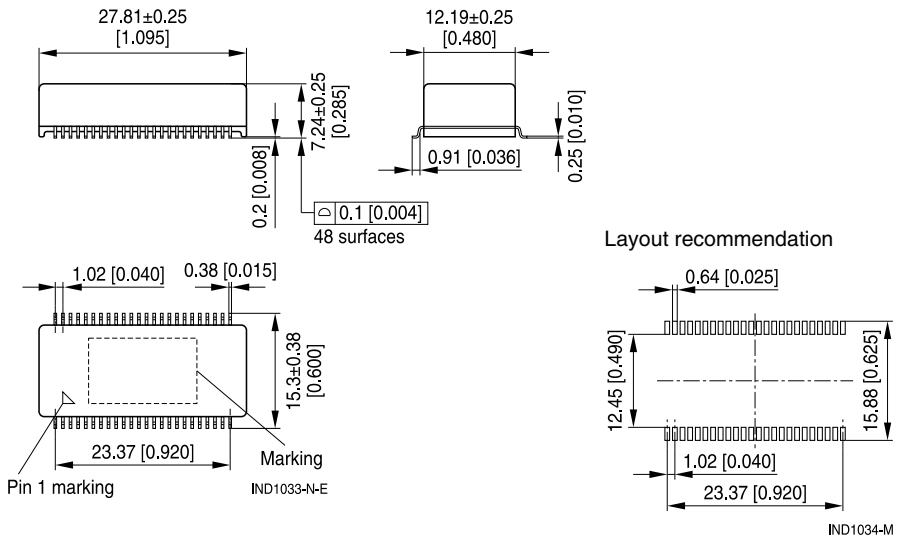
#### Marking

- EPCOS, middle block of ordering code, date code

#### Delivery mode and packing unit

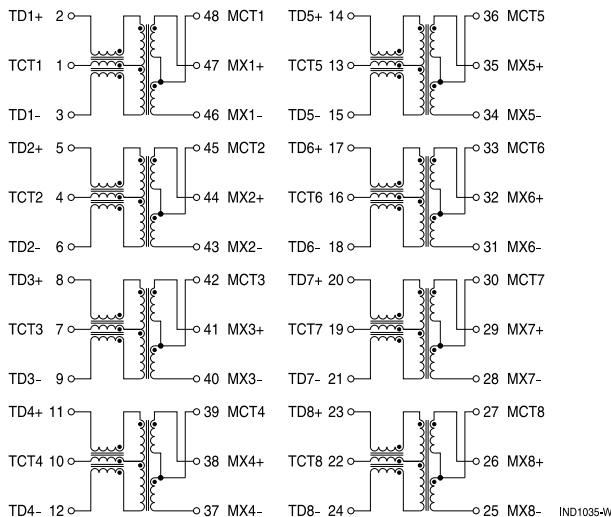
- 44-mm blister tape,  
330-mm  $\varnothing$  reel (cardboard packaging)
- Packing unit: 300 pcs./reel

#### Dimensional drawing



Dimensions in mm [inch]

Values without tolerances are nominal values for reference.

**SMD**
**Pinning**

**Characteristics and ordering code**

(electrical specifications at +25 °C)

Ordering code	B78476A8066A003	
Turns ratio (primary : secondary)	1CT : 1CT ±3%	
Inductance L	350 µH min.	100 kHz, 100 mV, 8 mA DC bias
Voltage test $V_{test}$	1500 V AC	50 Hz, 1 min
Insertion loss	-1.1 dB max.	0.1 MHz
	-1.0 dB max.	100 MHz
	-2.0 dB max.	125 MHz
Return loss	-18 dB min.	1 MHz ... 40 MHz
	-16 dB min.	50 MHz
	-12 dB min.	60 MHz ... 80 MHz
	-10 dB min.	100 MHz
Crosstalk	-43 dB min.	30 MHz
	-37 dB min.	60 MHz
	-33 dB min.	100 MHz
Differential to common-mode rejection (DCMR)	-43 dB min.	30 MHz
	-37 dB min.	60 MHz
	-33 dB min.	100 MHz
Operating temperature range	0 °C ... +70 °C	
Weight	Approx. 3.7 g	

SMD**Cautions and warnings**

- For soldering conditions of SMD components please refer to JEDEC J-STD-020D.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.  
Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
  - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
  - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
  - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

**Display of ordering codes for EPCOS products**

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2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified**. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or lifesaving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
3. **The warnings, cautions and product-specific notes must be observed.**
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## Important notes

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